RUIL&N

SMD3216 Series

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Description

The SMD3216 series has been especially designed to meet data transmission protection requirements. The optimized design features a high level of protection against fast rising transients usually caused by lightning disturbances. For use in high frequency data lines, the series offers ultra low capacitances and shows only marginally signal losses up to high frequencies. The devices are extremely reliable and are able to withstand high surge currents without destruction.



Electrical symbol



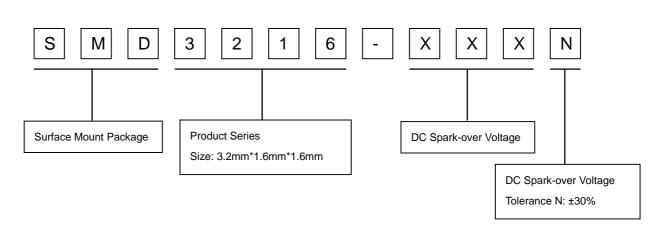
Features

- I Excellent response to fast rising transients
- I Stable breakdown voltage
- I GHz working frequency
- I 8/20µs Impulse current capability: 500A
- I Surface Mount package
- I Non-Radioactive
- I Ultra Low capacitance(<0.3pF) and insertion loss
- I Very Small Size(EIA 1206)
- I Storage and operational temperature: -40~+90°C

Applications

- I Ethernet, PoE, xDSL
- I Cable modem, splitters, line cards
- I Wireless antenna protection
- I CATV equipment
- I Switching power supply

Part Number Code



Specifications are subject to change without notice. Please refer to http://www.ruilon.com.cn for current information.

Version: A3/2023-11-02 File Number: SP-GDT-001



SMD3216 Series

Electrical Characteristics

Part Number	DC Spark-over Voltage ^{1) 2)} @100V/S				Capacitance @1 MHz	Glow Voltage	Arc Voltage	Service life		
				Insulation Resistance				Impulse Discharge		Impulse Withstanding Voltage
		100V/µS	1KV/µS	·		@10mA	@1A	Current @8/20µS		Capacity @10/700µS, 40W
		Max	Max	Min	Мах	Typical	Typical	±5 times	1 time	±5 times
	v	v	v	GΩ	pF	v	v	A	Α	KV
SMD3216-090N	90±30%	500	600	1	0.3	60	10	500		6
SMD3216-150N	150±30%	500	600	1	0.3	60	10	500		6
SMD3216-200N	200±30%	600	700	1	0.3	60	10	500		6
SMD3216-230N	230±30%	600	700	1	0.3	60	10	500		6
SMD3216-300N	300±30%	700	800	1	0.3	60	10	500		6
SMD3216-350N	350±30%	750	850	1	0.3	60	10	500		6
SMD3216-400N	400±30%	800	900	1	0.3	60	10	500		6
SMD3216-420N	420±30%	850	950	1	0.3	60	10	500		6
SMD3216-470N	470±30%	900	1000	1	0.3	60	10	500		6
SMD3216-600N	600±30%	1000	1200	1	0.3	60	10	500		6
Glow to Arc transition Current				<0.1A	<0.1A					
Weight			~0.03g	~0.03g						
Operation and storage temperature			40~+9	-40~+90°C						
Climatic category (IEC 60068-1)			40/90/2	40/90/21						
Marking			Withou	Without						
Surface treatment			Matte-t	Matte-tin plated						
Moisture sensitivity level 4)			1							

¹⁾ At delivery AQL 0.65 level II, DIN ISO 2859.

²⁾ In ionized mode.

³⁾ Insulation Resistance Measuring Voltage:

75V~150V at DC 50V

Other at DC 100V

⁴⁾ Tests according to JEDEC J-STD-020.

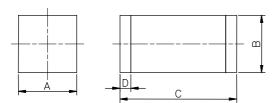
Terms in accordance with ITU-T K.12, IEC 61643-311, GB/T 9043, GB/T18802.311.

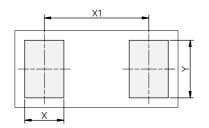
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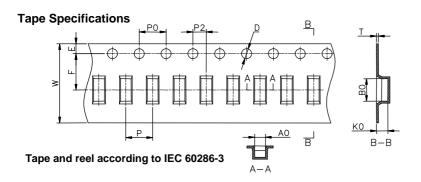
Dimensions



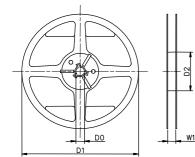


Recommended Soldering Pad Layout

Packaging Information

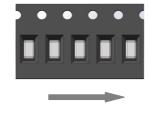


Reel Specifications



Packaging Quantity:

- 2,000 PCS per reel (7") 4 reels per inner box
- 8,000 PCS per inner box



Direction of Unreeling

Symbol	Millimeters	Inches
Α	1.6±0.2	0.063±0.008
В	1.6±0.2	0.063±0.008
С	3.2±0.3	0.126±0.012
D	0.3±0.1	0.012±0.004
х	1.3	0.051
X1	3.3	0.130
Y	1.8	0.071

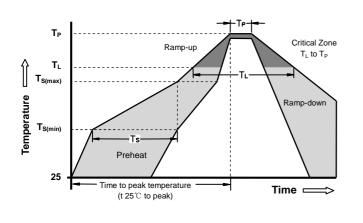
Symbol	Millimeters	Inches		
w	12±0.3	0.472±0.012		
A0	1.86±0.1	0.073±0.004		
B0	3.6±0.1	0.142±0.004		
K0	1.7±0.1	0.067±0.004		
Р	4.0±0.1	0.157±0.004		
F	5.5±0.1	0.217±0.004		
E	1.75±0.1	0.069±0.004		
D	1.5+0.1/-0.0	0.059+0.004/-0.0		
P0	4±0.1	0.157±0.004		
P2	2±0.1	0.079±0.004		
т	0.35±0.05	0.014±0.002		
D0	13.3±0.15	0.524±0.006		
D1	178±2	7.007±0.079		
D2	60+1/-2	2.362+0.039/-0.079		
W1	12.5±0.4	0.492±0.016		

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Gas Discharge Tubes (GDT)

SMD3216 Series

Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Condition		Pb - Free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Preheat	-Temperature Max (T _{s(max)})	200°C		
	- Time (min to max) (t _s)	60 -180 Seconds		
Average ramp to peak) up rate (Liquids Temp T _L)	3°C/second max		
T _{S(max)} to TL - Ramp-up Rate		5°C/second max		
Reflow	 Temperature (T_L) (Liquids) 	217°C		
	- Time (min to max) (t _s)	60 -150 Seconds		
Peak Temperature (T _P)		260 +0/-5°C		
Time within 5°C of actual peak Temperature (t _p)		10 - 30 Seconds		

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

Terms and definitions

NO.	ltem	Definitions	
1	Gas discharge tube(GDT)	A gap, or several gaps, in an enclosed discharge medium, other than air at atmospheric pressure, designed to protect apparatus or personnel, or both, from high transient voltages. Also referred to as "gas tube surge arrester".	
2	DC Spark-over Voltage	The voltage at which the gas discharge tube sparks over with slowly increasing d.c. voltage.	
3	Impulse Spark-over Voltage	The highest voltage which appears across the terminals of a gas discharge tube in the period between the application of an impulse of given wave-shape and the time when current begins to flow.	
5	Arc voltage	Voltage drop across the GDT during arc current flow.	
6	Glow voltage	Peak value of voltage drop across the GDT when a glow current is flowing.	
7	Impulse discharge current 8/20µs	Current impulse with a nominal virtual front time of 8 μs and a nominal time to half-value of 20 $\mu s.$	
8	Alternating Discharge Current	The rms value of an approximately sinusoidal alternating current passing through the gas discharge tube.	
9	Insulation Resistance	Insulation resistance shall be measured from each terminal to every other terminal of the GDT. The test is performed with DC50V when normal spark-over Voltage 70~150V, others with DC100V.	
10	Capacitance	The capacitance shall be measured once at 1 MHz between all terminals unless otherwise specified.	

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Cautions and warnings

- I Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- I Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- I Surge arresters must be handled with care and must not be dropped.
- I Do not continue to use damaged surge arresters.
- I The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- I SMD surge arresters should be soldered within 24 month after shipment.